

Device Material Content

5555 NE Moore Ct. Assembly: ASEK Hillsboro OR 97124 Package Code: Size (mm): 19 x 19 custreq@latticesemi.com 484 caBGA BG484 Lead pitch (mm): 0.8 Package: **Total Device Weight** 0.911 Grams MSL: 3 **Products:** LCMXO3-9400 June, 2022 Reflow max (°C): 260 % of Total % of Total Weight (g) Weight (g) Substance CAS# % of Subst. Notes / Assumptions: Pkg. Wt. Pkg. Wt. Die 0.0136 1.49% Die size: 4968 x 5092 um 1.49% 0.0136 7440-21-3 100.00% Silicon chip Mold Compound 52.67% 0.4798 Mold Compound: KE-G1250AHT 46.09% 60676-86-0 0.4198 Silica 87.50% 3.42% 0.0312 6.50% Epoxy resin 2.90% 0.0264 Phenol Resin 5.50% 0.50% 0.26% 0.0024 Carbon Black 1333-86-4 D/A Epoxy 0.21% 0.0019 Die attach epoxy: Henkel 2100A 0.17% 0.00151 Silver 7440-22-4 80.00% 0.04% 0.00038 20.00% Esters & resins Wire 0.85% 0.0077 CuPdAu+ 0.821%0.00748 Copper (Cu) 7440-50-8 96.55% 0.026% 0.00024 Palladium (Pd) 7440-05-3 3.10% 0.003% 7440-57-5 0.35% 0.00003 Gold (Au) Solder Balls 0.1684 18.49% SAC305 17.84% 0.1625 Tin (Sn) 7440-31-5 96.50% Silver (Ag) 0.55% 0.0051 7440-22-4 3.00% 0.09% 0.0008 Copper (Cu) 7440-50-8 0.50% Substrate 16.53% 0.1506 BT Resin CCL-HL832NX-A 5.29% 0.0482 BT Resins 32.00% 65997-17-3 11.24% 0.1024 Glass fiber 68.00% Foil 5.82% 0.0530 4.77% 0.0434 7440-50-8 82.00% Copper 0.88% 7440-02-0 15.10% 0.0080Nickel 0.17% 0.0015 Gold 7440-57-5 2.91% Solder Mask 3.94% 0.0359 Solder mask PSR4000 AUS 320 0.93% 0.0084 Solvent naphtha (petroleum) 64742-94-5 23.52% 38.20% 1.51% 0.0137 Phosphinoxide derivative 14807-96-6 Talc (containing no asbestiform fibers) 14.70% 0.58% 0.0053 0.58% 0.0053 Epoxy Resin 85954-11-6 14.70% 0.35% 0.0032 Barium Sulfate 7727-43-7 8.88%

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